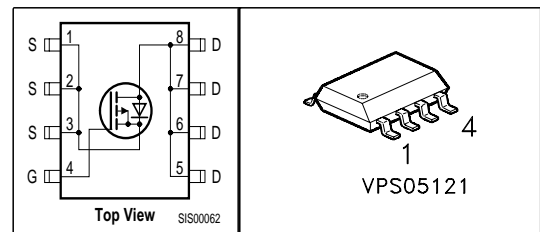


**SIPMOS® Power-Transistor**
**Features**

- P-Channel
- Enhancement mode
- Avalanche rated
- $dv/dt$  rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen-free according to IEC61249-2-21

**Product Summary**

Drain source voltage	$V_{DS}$	-60	V
Drain-source on-state resistance	$R_{DS(on)}$	0.13	$\Omega$
Continuous drain current	$I_D$	-3.44	A



<b>Type</b>	<b>Package</b>	<b>Lead free</b>
BSO613SPV G	PG-SO 8	Yes


**Maximum Ratings, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Value	Unit
Continuous drain current $T_A = 25\text{ °C}$	$I_D$	-3.44	A
Pulsed drain current $T_A = 25\text{ °C}$	$I_{D\text{ puls}}$	-13.8	
Avalanche energy, single pulse $I_D = -3.44\text{ A}$ , $V_{DD} = -25\text{ V}$ , $R_{GS} = 25\text{ }\Omega$	$E_{AS}$	150	mJ
Avalanche energy, periodic limited by $T_{jmax}$	$E_{AR}$	0.25	
Reverse diode $dv/dt$ $I_S = -3.44\text{ A}$ , $V_{DS} = -48\text{ V}$ , $di/dt = 200\text{ A}/\mu\text{s}$ , $T_{jmax} = 150\text{ °C}$	$dv/dt$	6	kV/ $\mu\text{s}$
Gate source voltage	$V_{GS}$	$\pm 20$	V
Power dissipation $T_A = 25\text{ °C}$	$P_{tot}$	2.5	W
Operating and storage temperature	$T_j, T_{stg}$	-55... +150	$^{\circ}\text{C}$
IEC climatic category; DIN IEC 68-1		55/150/56	

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - soldering point (Pin 4)	$R_{thJS}$	-	-	25	K/W
SMD version, device on PCB: @ min. footprint; $t \leq 10$ sec. @ 6 cm <sup>2</sup> cooling area <sup>1)</sup> ; $t \leq 10$ sec.	$R_{thJA}$	-	-	100	
		-	-	50	

**Electrical Characteristics, at  $T_j = 25$  °C, unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain- source breakdown voltage $V_{GS} = 0$ V, $I_D = -250$ $\mu$ A	$V_{(BR)DSS}$	-60	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 1$ mA	$V_{GS(th)}$	-2.1	-3	-4	
Zero gate voltage drain current $V_{DS} = -60$ V, $V_{GS} = 0$ V, $T_j = 25$ °C $V_{DS} = -60$ V, $V_{GS} = 0$ V, $T_j = 125$ °C	$I_{DSS}$	-	-0.1	-1	$\mu$ A
Gate-source leakage current $V_{GS} = -20$ V, $V_{DS} = 0$ V	$I_{GSS}$	-	-10	-100	
Drain-source on-state resistance $V_{GS} = -10$ V, $I_D = -3.44$ A	$R_{DS(on)}$	-	0.11	0.13	$\Omega$

<sup>1</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu$ m thick) copper area for drain connection. PCB is vertical without blown air.

**Electrical Characteristics, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = -3.44\text{ A}$	$g_{fs}$	2.2	4.4	-	S
Input capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = -25\text{ V}$ , $f = 1\text{ MHz}$	$C_{iss}$	-	700	875	pF
Output capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = -25\text{ V}$ , $f = 1\text{ MHz}$	$C_{oss}$	-	235	295	
Reverse transfer capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = -25\text{ V}$ , $f = 1\text{ MHz}$	$C_{rss}$	-	95	120	
Turn-on delay time $V_{DD} = -30\text{ V}$ , $V_{GS} = -10\text{ V}$ , $I_D = -3.44\text{ A}$ , $R_G = 2.7\ \Omega$	$t_{d(on)}$	-	10	15	ns
Rise time $V_{DD} = -30\text{ V}$ , $V_{GS} = -10\text{ V}$ , $I_D = -3.44\text{ A}$ , $R_G = 2.7\ \Omega$	$t_r$	-	11	16.5	
Turn-off delay time $V_{DD} = -30\text{ V}$ , $V_{GS} = -10\text{ V}$ , $I_D = -3.44\text{ A}$ , $R_G = 2.7\ \Omega$	$t_{d(off)}$	-	32	48	
Fall time $V_{DD} = -30\text{ V}$ , $V_{GS} = -10\text{ V}$ , $I_D = -3.44\text{ A}$ , $R_G = 2.7\ \Omega$	$t_f$	-	12	18	

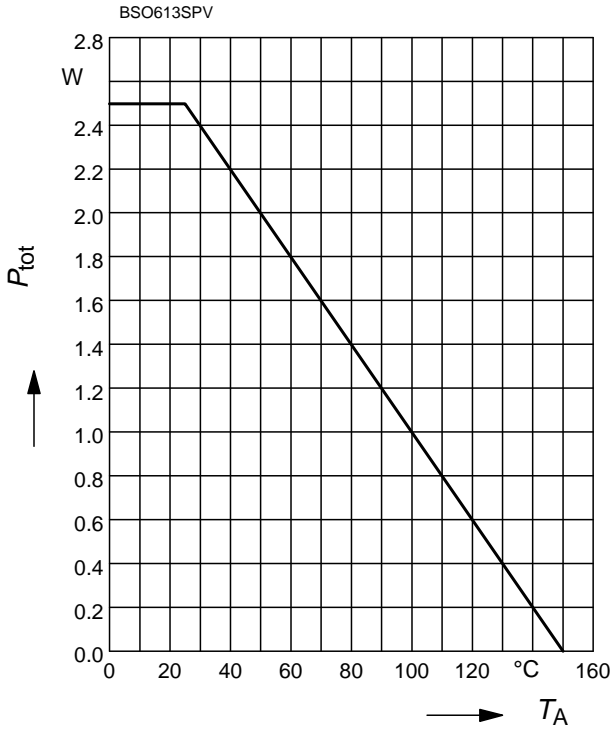
**Electrical Characteristics, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Gate to source charge $V_{DD} = -48\text{ V}$ , $I_D = -3.44\text{ A}$	$Q_{gs}$	-	1.6	2.4	nC
Gate to drain charge $V_{DD} = -48\text{ V}$ , $I_D = -3.44\text{ A}$	$Q_{gd}$	-	10	15	
Gate charge total $V_{DD} = -48\text{ V}$ , $I_D = -3.44\text{ A}$ , $V_{GS} = 0\text{ to }-10\text{ V}$	$Q_g$	-	20	30	
Gate plateau voltage $V_{DD} = -48\text{ V}$ , $I_D = -3.44\text{ A}$	$V_{(plateau)}$	-	-3.74	-	V

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Reverse Diode</b>					
Inverse diode continuous forward current $T_A = 25\text{ °C}$	$I_S$	-	-	-3.44	A
Inverse diode direct current,pulsed $T_A = 25\text{ °C}$	$I_{SM}$	-	-	-13.8	
Inverse diode forward voltage $V_{GS} = 0\text{ V}$ , $I_F = -3.44\text{ A}$	$V_{SD}$	-	-0.87	-1.16	V
Reverse recovery time $V_R = -30\text{ V}$ , $I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$	$t_{rr}$	-	56	84	ns
Reverse recovery charge $V_R = -30\text{ V}$ , $I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$	$Q_{rr}$	-	38	57	nC

**Power Dissipation**

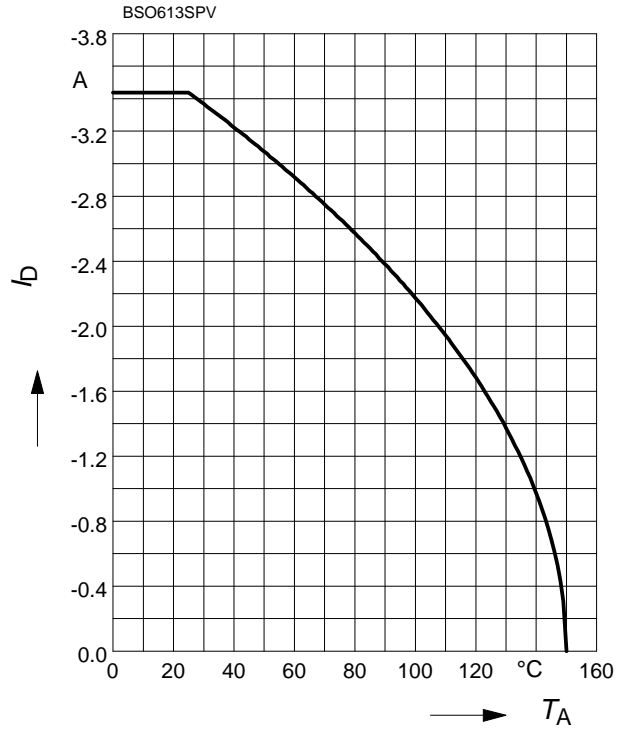
$P_{tot} = f(T_A)$



**Drain current**

$I_D = f(T_A)$

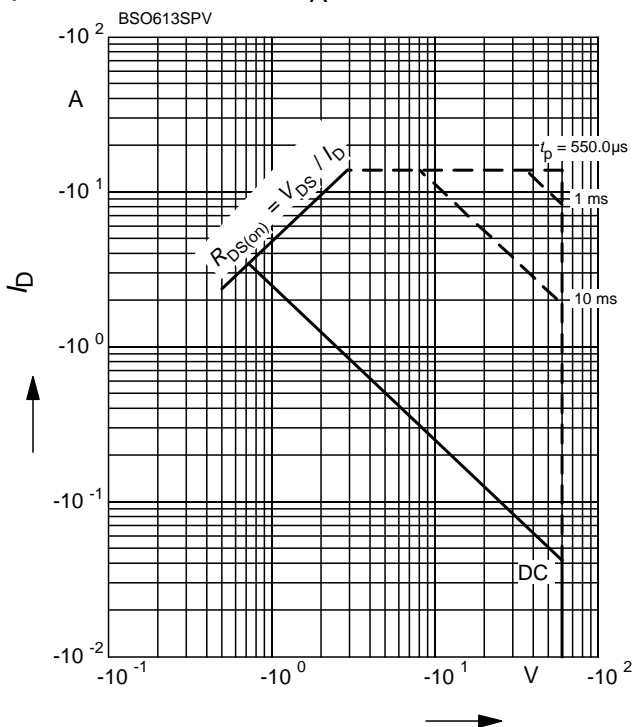
parameter:  $V_{GS} \geq 10\text{ V}$



**Safe operating area**

$I_D = f(V_{DS})$

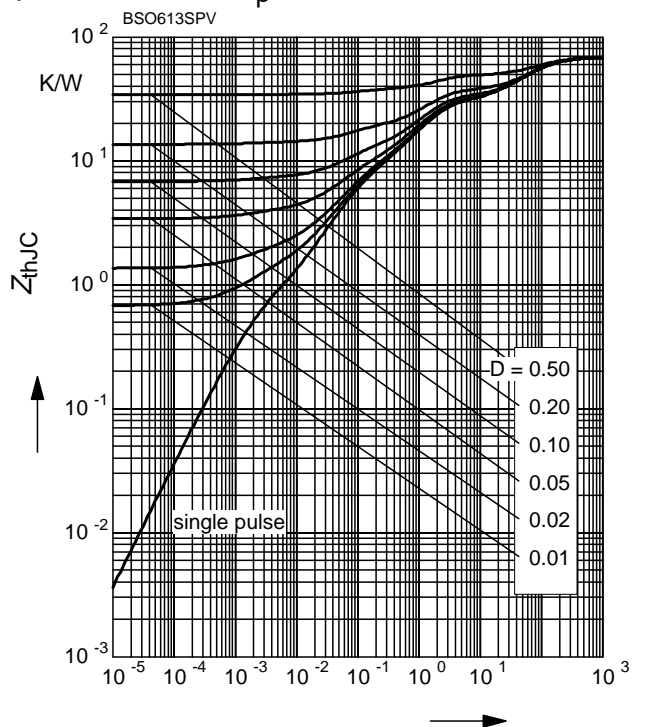
parameter :  $D = 0, T_A = 25\text{ °C}$



**Transient thermal impedance**

$Z_{thJC} = f(t_p)$

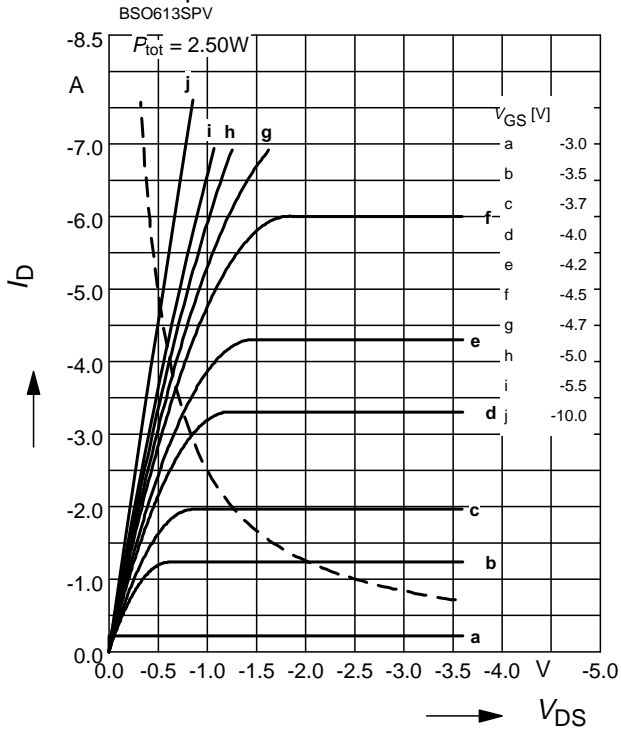
parameter :  $D = t_p/T$



**Typ. output characteristic**

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

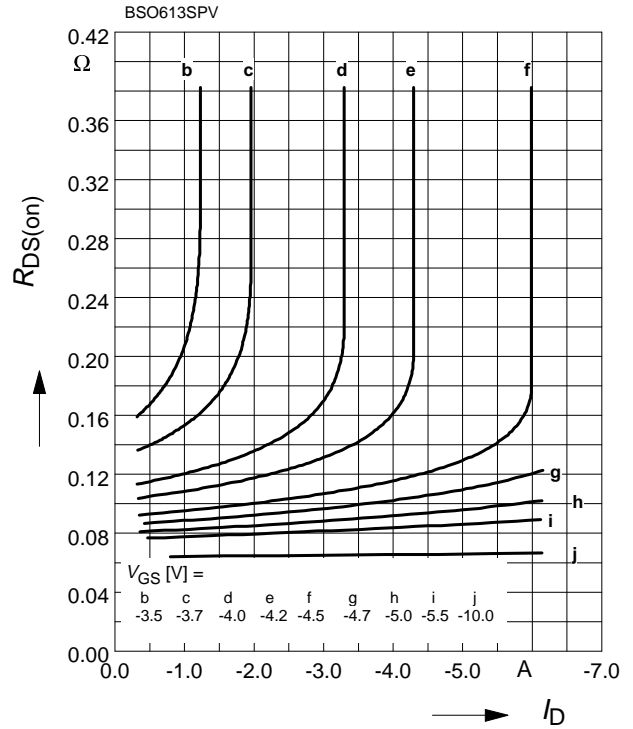
parameter:  $t_p = 80 \mu\text{s}$



**Typ. drain-source-on-resistance**

$R_{DS(on)} = f(I_D)$

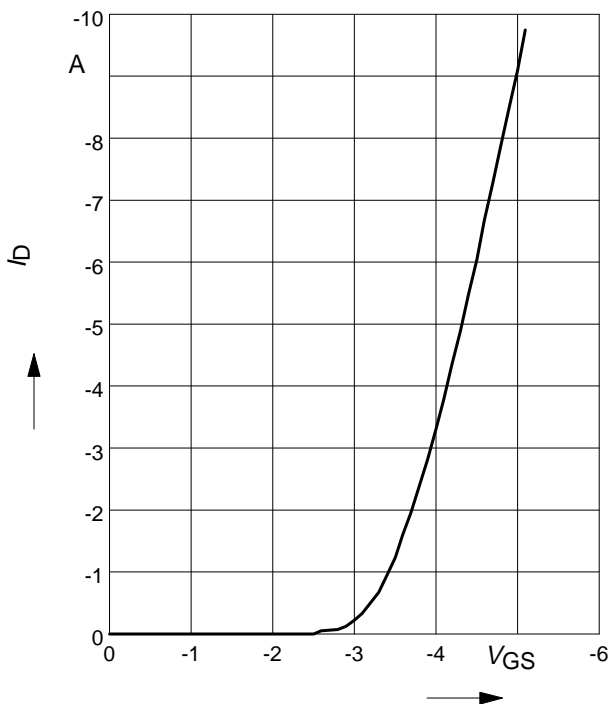
parameter:  $V_{GS}$



**Typ. transfer characteristics  $I_D = f(V_{GS})$**

$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

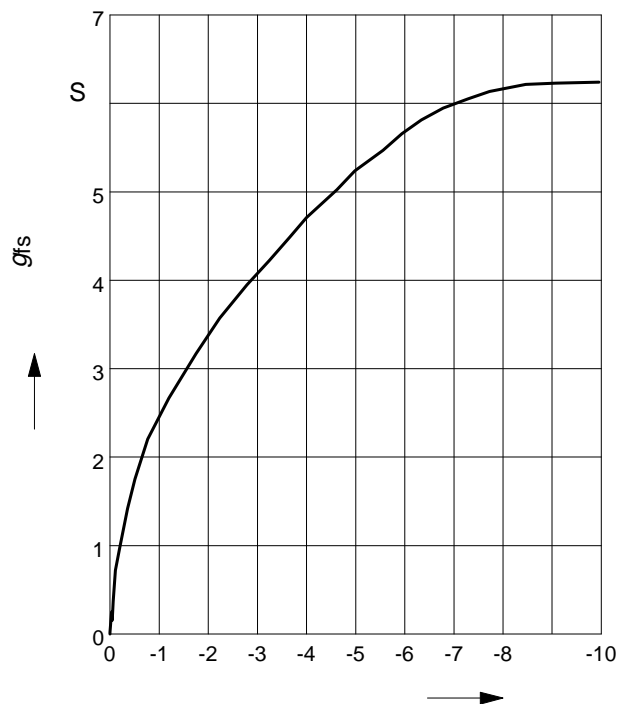
parameter:  $t_p = 80 \mu\text{s}$



**Typ. forward transconductance**

$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

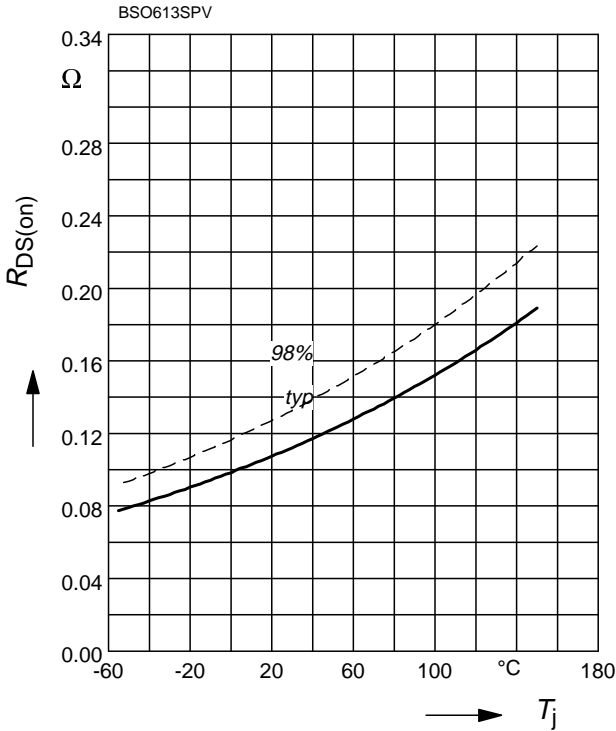
parameter:  $g_{fs}$



**Drain-source on-state resistance**

$$R_{DS(on)} = f(T_j)$$

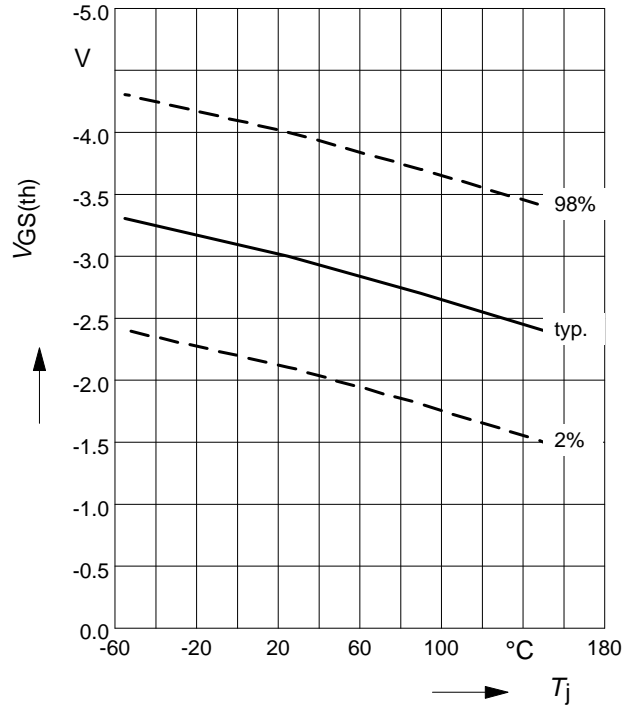
parameter:  $I_D = -3.44$  A,  $V_{GS} = -10$  V



**Gate threshold voltage**

$$V_{GS(th)} = f(T_j)$$

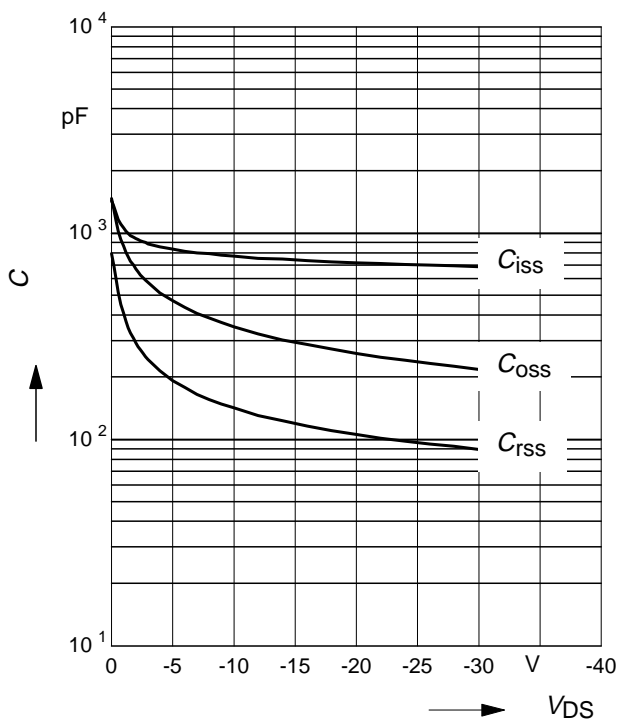
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 1$  mA



**Typ. capacitances**

$$C = f(V_{DS})$$

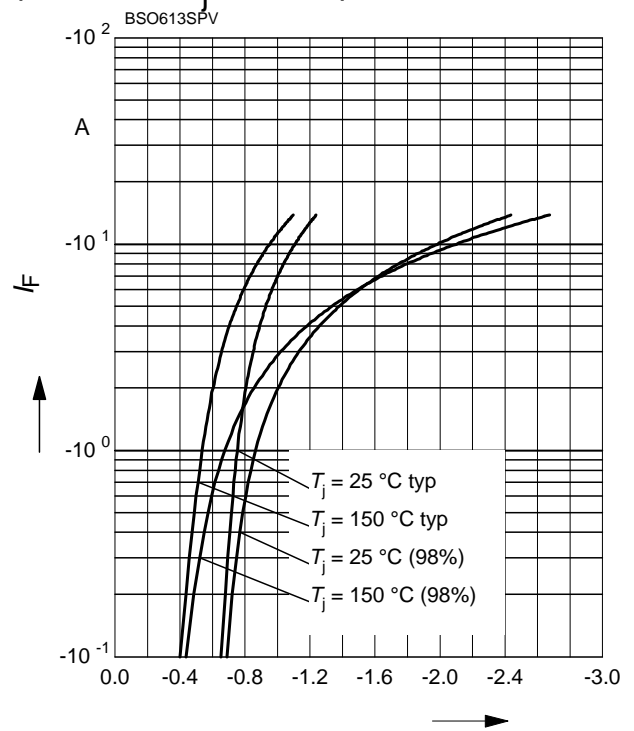
parameter:  $V_{GS}=0$ V,  $f=1$  MHz



**Forward characteristics of reverse diode**

$$I_F = f(V_{SD})$$

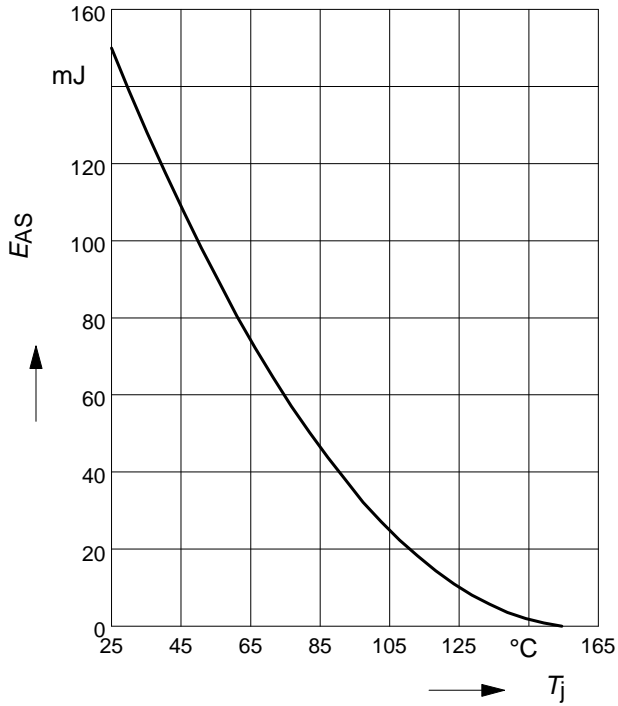
parameter:  $T_j$ ,  $t_p = 80$   $\mu$ s



**Avalanche energy**

$$E_{AS} = f(T_j)$$

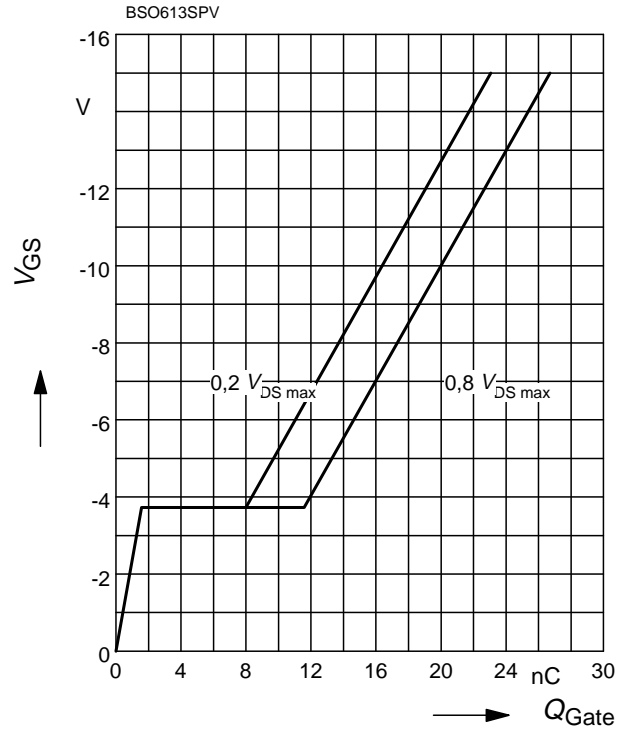
para.:  $I_D = -3.44 \text{ A}$  ,  $V_{DD} = -25 \text{ V}$  ,  $R_{GS} = 25$



**Typ. gate charge**

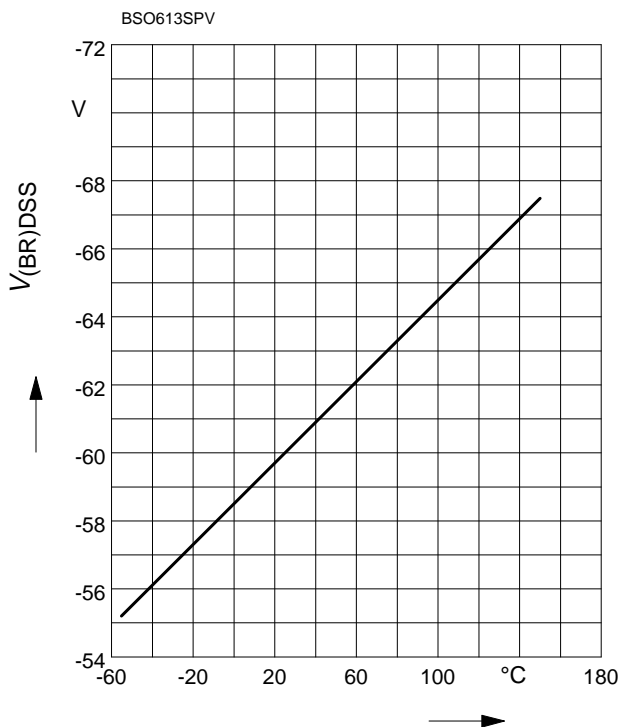
$$V_{GS} = f(Q_{Gate})$$

parameter:  $I_D = -3.44 \text{ A}$  pulsed



**Drain-source breakdown voltage**

$$V_{(BR)DSS} = f(T_j)$$





## Revision History

BSO613SPV

**Revision: 2019-07-31, Rev. 2.0**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2019-07-31	Release of final version

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